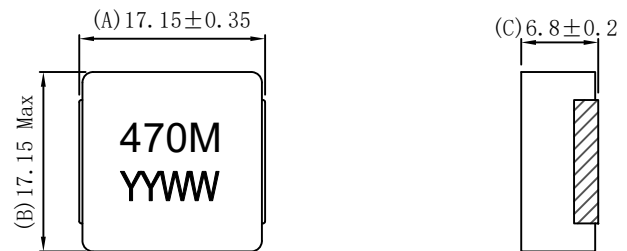
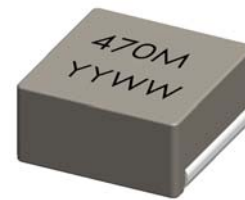


FEATURES

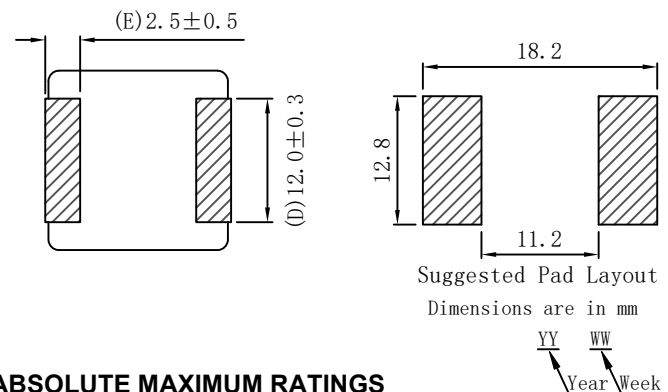
- RoHS compliant, UL94V-0
- Small size (17.50*17.15mm Max), low profile (Height: 7.0mm Max)
- Inductance range from 0.47uH to 100.0uH
- Surface mount design
- Magnetic shield construction
- Ultra low buzz noise due to composite construction
- Handle transient current spikes without saturation
- Excellent temperature stability for inductance and saturation
- Tape & reel packing
- Solder profile acc. J-STD-020D

APPLICATIONS

- Low profile, high current power supplies
- DC/DC converters
- Battery powered devices
- PDA/notebook/desktop/server applications



Part number	Inductance ($\mu\text{H} \pm 20\%$)	DCR (m Ω) @25°C		Irms (A)	Isat (A)
		TYP.	MAX.		
MHA1770NSGR47M	0.47	0.80	0.95	60.00	75.00
MHA1770NSG1R0M	1.00	1.20	1.45	49.50	54.00
MHA1770NSG1R5M	1.50	1.85	2.15	40.00	40.00
MHA1770NSG2R2M	2.20	2.15	2.50	32.00	34.00
MHA1770NSG3R3M	3.30	3.40	3.95	26.00	26.00
MHA1770NSG4R7M	4.70	4.12	4.72	24.00	24.00
MHA1770NSG6R8M	6.80	6.55	7.55	20.00	22.00
MHA1770NSG8R2M	8.20	8.10	8.70	15.00	20.00
MHA1770NSG100M	10.0	9.30	10.00	14.00	18.00
MHA1770NSG150M	15.0	14.50	15.00	11.00	13.00
MHA1770NSG200M	20.0	19.50	21.90	9.70	12.00
MHA1770NSG220M	22.0	20.50	23.00	9.50	11.00
MHA1770NSG330M	33.0	35.10	37.00	9.00	10.00
MHA1770NSG470M	47.0	41.00	47.00	6.80	7.50
MHA1770NSG680M	68.0	74.00	85.00	5.20	6.50
MHA1770NSG101M	100.0	110.0	130.0	3.30	5.00



ABSOLUTE MAXIMUM RATINGS

Operating temperature rang -55°C to +125°C
(Including coil' self temperature rise)
Storage temperature rang -55°C to +125°C

SOLDERING INFORMATION

Peak reflow temperature 250°C
Pin finish tin

PACKAGING INFORMATION

Tape & Reel 300pcs per reel
Weight 11.8g/pcs

Notes

1. Electrical specification at 25°C.
2. Inductance tested at 100 kHz, 0.25Vrms.
3. Irms is the current that caused a approximate 40°C temperature rise from 25°C ambient.
4. Isat is the DC current at which inductance drop approximately 30% from its value without current.
5. The part temperature (ambient + temp. rise) should not exceed 125°C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.